

## Initial Product/Process Change Notification Document #: IPCN20981XB

Issue Date: 15 July 2015

Title of Change:	Copper wire conversion and mold compound change for LA72910V/LV72910VL/LA72914V/LA72914VL		
Proposed first ship date:	15 January 2016		
Contact information:	Contact your local ON Semiconductor Sales Office or		

The test items with \* mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.

## Judgment Criteria:

Judgment Criteria are due to the limits of the electrical characteristics in the detail specification

TEM001091 Rev. E Page 1 of 2



## Initial Product/Process Change Notification Document #: IPCN20981XB Issue Date: 15 July 2015

List of affected Standard Parts:				
Part Number	Qualification Vehicle			
LA72910V-TLM-H	147704011 7144 5			
LA72914V-TLM-H	LA72910VL-TLM-E			

TEM001091 Rev. E Page 2 of 2